

We claim:

1. A support element for a semiconductor package, the support element comprising:

- 5 (a) a first surface having a plurality of conductors;
- (b) a second surface having a plurality of die attach areas, wherein at least one of the die attach areas comprises a defective die attach area;
- (c) the die attach areas including wire bond slots extending from the first surface to the second surface of the support element so as to form
- 10 openings therethrough; and
- (d) a cover member attached to the at least one defective die attach area so as to cover at least a portion of the wire bond slot, wherein the cover member does not comprise a functional die.

15 2. The support element of claim 1, wherein the cover member comprises self-adhesive tape.

3. The support member of claim 1, wherein the cover member comprises a defective die.

20 4. The support member of claim 1, wherein the cover member covers from about 80% to about 90% of the wire bond slot.

25 5. The support member of claim 1, wherein the cover member covers at least 70% of an opening formed by the wire bond slot.

6. A support element comprising:

(a) a plurality of integrally connected substrates, the substrates forming a first surface and a second surface;

30 (b) at least one substrate forming a defective die attach area on the second surface of the substrate;

15

(c) the at least one substrate having a wire bond slot forming an opening through the substrate extending from the first surface to the second surface; and

(d) a cover member attached to the at least one substrate at the defective die attach area so as to cover at least a portion of the wire bond slot, wherein the cover member does not comprise a functional die.

7. The support element of claim 6, wherein the first surface further includes a plurality of conductors.

8. The support member of claim 6, wherein the cover member comprises tape.

9. The support member of claim 6, wherein the cover member covers a majority of an opening formed by the wire bond slot.

10. A substrate of a support element, the substrate comprising:

(a) an insulating material having a first surface;

(b) a defective pattern of conductors on the first surface;

(c) a wire bond slot forming an opening through the substrate extending from the first surface to a second surface; and

(d) a cover member attached to the substrate on the second surface so as to cover at least a portion of the wire bond slot, wherein the cover member does not comprise a functional die.

11. The substrate of claim 10, wherein the cover member comprises self-adhesive tape.

12. The substrate of claim 10, wherein the cover member comprises a defective die.

13. The substrate of claim 10, wherein the cover member covers from about 80% to about 90% of the wire bond slot.

14. The substrate of claim 10, wherein the cover member covers at least 70% of an opening formed by the wire bond slot.

15. A support element comprising:

(a) a strip of insulating material forming a plurality of integrally connected substrates;

(b) a first surface having electrical circuitry at each substrate, wherein at least substrate includes defective electrical circuitry;

(c) a second surface having a substantially planar die attach surface at each substrate; and

(d) a cover member placed on the at least one substrate having defective electrical circuitry, wherein the cover member covers at least a portion of an opening extending through the substrate and does not comprise a functional die.

16. The support member of claim 15, wherein the cover member covers from about 80% to about 90% of the opening.

17. The support element of claim 15, wherein the cover member comprises self-adhesive tape.

18. The support element of claim 15, wherein the cover member comprises a defective die.

19. A support element for a semiconductor package, the support element comprising:

(a) a first surface having a plurality of conductors;

(b) a second surface having a plurality of die attach areas, wherein at least one of the die attach areas comprises a defective die attach area;

(c) the die attach areas including wire bond slots extending from the first surface to the second surface of the support element so as to form

5 openings therethrough; and

(d) a cover member attached to the at least one defective die attach area so as to cover enough of the opening formed by the wire bond slot so as to substantially eliminate bleeding when the support element is encapsulated, wherein the cover member does not comprise a functional die.

10 20. The support element of claim 19, wherein the cover element does not cover enough of the opening so as to cause a negative pressure zone at the wire bond slot when the support element is encapsulated with a liquid plastic.

15 21. A support element comprising:

(a) a plurality of integrally connected substrates, the substrates forming a first surface and a second surface;

(b) at least one substrate forming a defective die attach area on the second surface of the substrate;

20 (c) the at least one substrate having a wire bond slot forming an opening through the substrate extending from the first surface to the second surface; and

(d) a cover member attached to the at least one substrate at the defective die attach area so as to cover a majority of the opening formed by the
25 wire bond slot, wherein the cover member does not comprise a functional die.

22. A support element comprising:

(a) a plurality of integrally connected substrates, the substrates forming a first surface and a second surface;

30 (b) at least one substrate forming a defective die attach area on the second surface of the substrate;

(c) the at least one substrate having a wire bond slot forming an opening through the substrate extending from the first surface to the second surface; and

5 (d) a cover member attached to the at least one substrate at the defective die attach area so as to cover from about 70 percent to about 100 percent of the opening formed by the wire bond slot, wherein the cover member does not comprise a functional die.

23. A substrate of a support element, the substrate comprising:

10 (a) a first surface having a pattern of conductors;
(b) a second surface having a die attach area with defective electrical circuitry;

(c) a wire bond slot forming an opening through the substrate extending from the first surface to the second surface; and

15 (d) a cover member attached to the substrate on the second surface so as to cover a majority of the opening formed by the wire bond slot, wherein the cover member does not comprise a functional die.

20 24. A support element for a semiconductor package, the support element comprising:

(a) a first surface having a plurality of conductors;
(b) a second surface having a plurality of die attach areas, wherein at least one of the die attach areas comprises a defective die attach area;

25 (c) the die attach areas including wire bond slots extending from the first surface to the second surface of the support element so as to form openings therethrough; and

(d) a defective die attached to the at least one defective die attach area so as to cover at least a portion of the wire bond slot.

25. The support element of claim 24, wherein the cover member comprises heat-sensitive tape covering a majority of an opening formed by a wire bond slot.

5 26. The support element of claim 24, wherein the cover member comprises a defective die covering from about 80% to about 90% of an opening formed by a wire bond slot.

10 27. A support element for a semiconductor package, the support element comprising:

- (a) a first surface having a plurality of conductors;
- (b) a second surface having a plurality of die attach areas, wherein at least one of the die attach areas comprises a defective die attach area;
- (c) the die attach areas including wire bond slots extending from the
- 15 first surface to the second surface of the support element so as to form openings therethrough; and
- (d) tape attached to the at least one defective die attach area so as to cover at least a portion of the wire bond slot.

20 28. A substrate of a support element, the substrate comprising:

- (a) a first surface having a pattern of conductors;
- (b) a second surface having a die attach area with defective electrical circuitry;
- (c) a wire bond slot forming an opening through the substrate
- 25 extending from the first surface to the second surface; and
- (d) a defective die attached to the substrate on the second surface so as to cover at least a portion of the wire bond slot.

30 29. A support element for a semiconductor package, the support element comprising:

- (a) a first surface having a plurality of conductors;

(b) a second surface having a plurality of die attach sites, wherein a first die attach site is defective and a second die attach site is functional;

(c) a plurality of integrally connected substrates formed by the first and second surfaces; and

5 (d) the substrates including wire bond slots extending from the first surface to the second surface of the support element so as to form openings therethrough, wherein there is at least one opening formed at the first and the second die attach sites;

10 (e) a cover member attached to the first die attach site so as to cover from about 70% to about 100% of the opening.

30. A defective semiconductor package comprising:

(a) a substrate having a first surface with a pattern of conductors;

15 (b) the substrate having a second surface including a defective die attach site;

(c) a wire bond slot forming an opening through the substrate extending from the first surface to the second surface; and

20 (d) a cover member attached to the substrate on the second surface so as to cover at least a portion of the opening, wherein the cover member does not comprise a functional die.

31. The defective semiconductor package of claim 30, wherein the cover member comprises tape.

25 32. The defective semiconductor package of claim 30, wherein the cover member covers a majority of the opening.

33. A method of fabricating a support element for a semiconductor package, the method comprising:

30 (a) forming a plurality of conductors on a first surface of an insulating material;

(b) forming a plurality of die attach areas on a second surface of the insulating material, wherein at least one of the die attach areas comprises a defective die attach area;

5 (c) forming wire bond slots to extend from the first surface to the second surface of the insulating material so as to form openings therethrough; and

(d) attaching a defective die to the at least one defective die attach area so as to cover at least a portion of the wire bond slot.

10 34. A method of fabricating a semiconductor package comprising:

(a) forming a plurality of conductors on a first surface of an insulating material;

15 (b) forming a plurality of die attach sites on a second surface of the insulating material, wherein at least one of the die attach sites comprises a defective die attach site;

(c) forming wire bond slots to extend from the first surface to the second surface of the insulating material so as to form openings therethrough;

(d) attaching a cover member to the at least one defective die attach site so as to cover at least a portion of the wire bond slot;

20 (e) attaching a functional die to at least one die attach site: and

(f) encapsulating the insulating material, cover member, and die with a plastic material.

25 35. A method of fabricating a semiconductor package comprising:

(a) forming a support element having at least one defective die site and at least one functional die site;

(b) attaching a cover member over an opening formed by a wire bond slot at the defective die site, wherein the cover member does not comprise a functional die; and

	1970	1971	1972	1973	1974	1975	1976	1977	1978	1979	1980	1981	1982	1983	1984	1985	1986	1987	1988	1989	1990	1991	1992	1993	1994	1995	1996	1997	1998	1999	2000	2001	2002	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014	2015	2016	2017	2018	2019	2020	2021	2022	2023	2024	2025	2026	2027	2028	2029	2030	2031	2032	2033	2034	2035	2036	2037	2038	2039	2040	2041	2042	2043	2044	2045	2046	2047	2048	2049	2050	2051	2052	2053	2054	2055	2056	2057	2058	2059	2060	2061	2062	2063	2064	2065	2066	2067	2068	2069	2070	2071	2072	2073	2074	2075	2076	2077	2078	2079	2080	2081	2082	2083	2084	2085	2086	2087	2088	2089	2090	2091	2092	2093	2094	2095	2096	2097	2098	2099	2100	2101	2102	2103	2104	2105	2106	2107	2108	2109	2110	2111	2112	2113	2114	2115	2116	2117	2118	2119	2120	2121	2122	2123	2124	2125	2126	2127	2128	2129	2130	2131	2132	2133	2134	2135	2136	2137	2138	2139	2140	2141	2142	2143	2144	2145	2146	2147	2148	2149	2150	2151	2152	2153	2154	2155	2156	2157	2158	2159	2160	2161	2162	2163	2164	2165	2166	2167	2168	2169	2170	2171	2172	2173	2174	2175	2176	2177	2178	2179	2180	2181	2182	2183	2184	2185	2186	2187	2188	2189	2190	2191	2192	2193	2194	2195	2196	2197	2198	2199	2200	2201	2202	2203	2204	2205	2206	2207	2208	2209	2210	2211	2212	2213	2214	2215	2216	2217	2218	2219	2220	2221	2222	2223	2224	2225	2226	2227	2228	2229	2230	2231	2232	2233	2234	2235	2236	2237	2238	2239	2240	2241	2242	2243	2244	2245	2246	2247	2248	2249	2250	2251	2252	2253	2254	2255	2256	2257	2258	2259	2260	2261	2262	2263	2264	2265	2266	2267	2268	2269	2270	2271	2272	2273	2274	2275	2276	2277	2278	2279	2280	2281	2282	2283	2284	2285	2286	2287	2288	2289	2290	2291	2292	2293	2294	2295	2296	2297	2298	2299	2300	2301	2302	2303	2304	2305	2306	2307	2308	2309	2310	2311	2312	2313	2314	2315	2316	2317	2318	2319	2320	2321	2322	2323	2324	2325	2326	2327	2328	2329	2330	2331	2332	2333	2334	2335	2336	2337	2338	2339	2340	2341	2342	2343	2344	2345	2346	2347	2348	2349	2350	2351	2352	2353	2354	2355	2356	2357	2358	2359	2360	2361	2362	2363	2364	2365	2366	2367	2368	2369	2370	2371	2372	2373	2374	2375	2376	2377	2378	2379	2380	2381	2382	2383	2384	2385	2386	2387	2388	2389	2390	2391	2392	2393	2394	2395	2396	2397	2398	2399	2400	2401	2402	2403	2404	2405	2406	2407	2408	2409	2410	2411	2412	2413	2414	2415	2416	2417	2418	2419	2420	2421	2422	2
--	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	------	---